

CATEGORY	DESCRIPTION	P/N #
CONNECTOR	D-SUB 25P(Two Layer, R/A, T/H)	DB2F2F-B1XX0-XXXX

REV.	ECN NO	DESCRIPTION	REVISED	DATE
R01		New Release	JXM	2009.05.07

**SPECIFICATIONS**

- CONTACT CURRENT RATING:3 Amperes.
- DIELECTRIC WITHSTANDING VOLTAGE:AC 1000/60sec.r.m.s.
- INSULATION RESISTANCE:5000 Medohms MIN.AT DC 500V.
- CONTACT RESISTANCE:25 Milliohms MAX.
- TEMPERATURE:-55°C TO +105°C.
- GROUNDING SCREW TORQUE:3kg MIN.
- SOLDER HEAT RESISTANCE:WAVE SOLDERING 260° 10sec.
- TO CONFORM TO THE "SONY" DIRECTIVE.
- GREEN PRODUCT IDENTIFICATION LABEL IN PACKING:
- PRESENT CRITICAL DIMENSIONS.

**G.P. PASS**

PART NO:

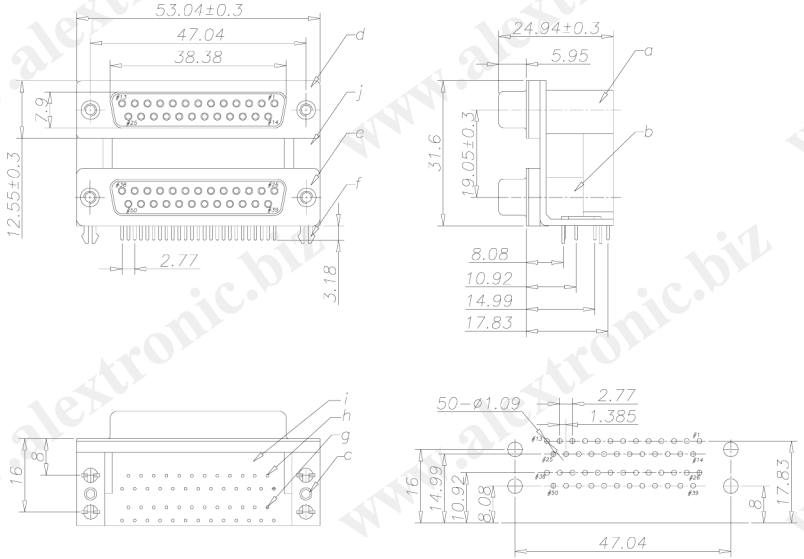
DB2F2F-B1XX0-XXXX

- 01.無螺絲
- 02.附螺絲
- 03.鍍螺絲

COLOR: Q0 H:BLACK C:BLACK

X	Shell Plating
1	Ni Plating

X	Terminal Plating
1	Gold Flash Plating



Recommend PCB Layout  
(Jack Top View)  
Tolerance: ±0.05mm  
Recommend PCB Thickness: 1.6mm

j	Holder	2	SPCC	Ni Plating
i	Cover	1	PBT UL94V-0	Black
h	Terminal #26~50	25	Brass	Gold Flash Plating
g	Terminal #1~25	25	Brass	Gold Flash Plating
f	Board Lock	2	SPCC	Tin Plating
e	Shell B	1	SPCC	Ni Plating
d	Shell A	1	SPCC	Ni Plating
c	Rivet	2	Brass	Ni Plating
b	Housing B	1	PBT UL94V-0	Black
a	Housing A	1	PBT UL94V-0	Black
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING & COLOR

**Product Drawing**  
**ALEXTRONIC**

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1 UNIT: mm	⊕ ⊖ DWG.NO:
	SIZE: A3 PAGE: 10F1	REV:R01
DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2	ANGLES: X :±2° X.X :±1°	APPROVED BY
		CHECKED BY
		PREPARED BY
	GG	WYX
		JXM
<b>CUSTOMER COPY</b>		